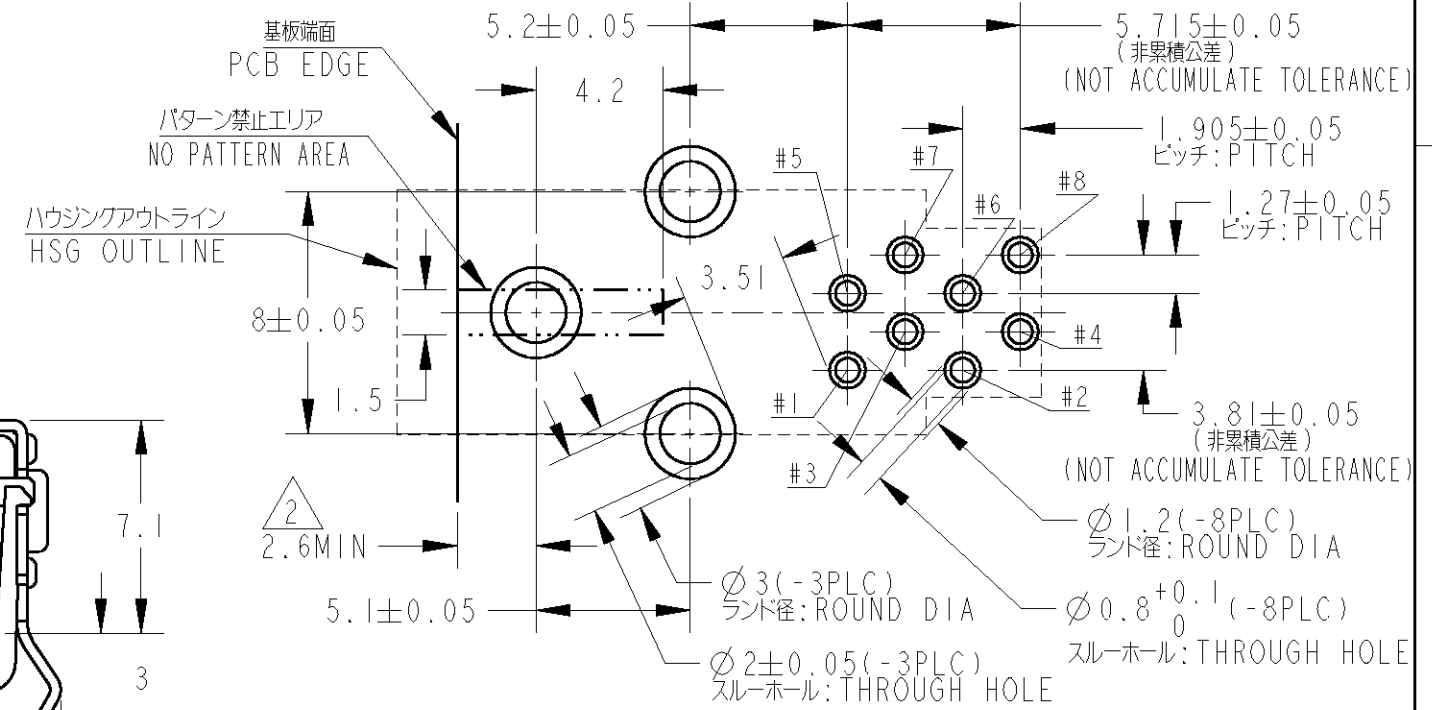
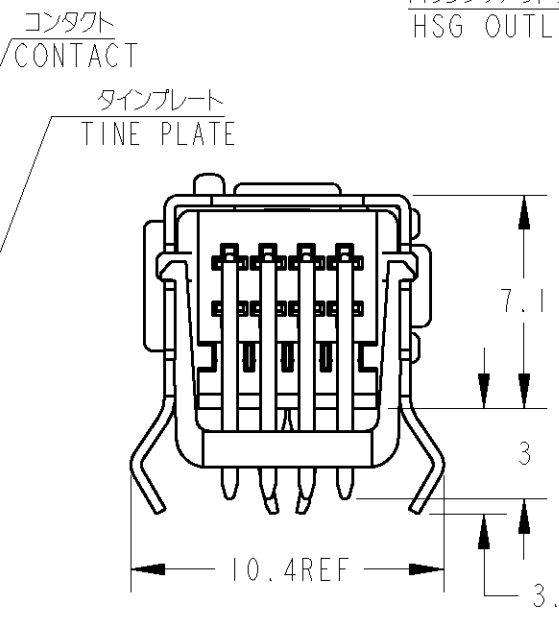
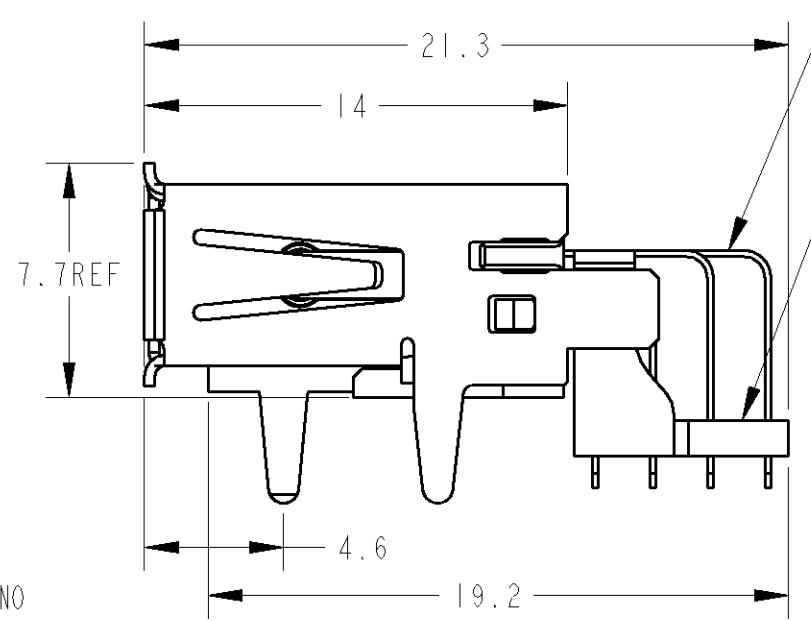
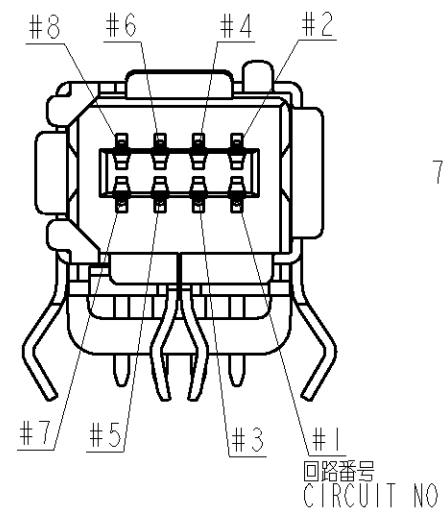
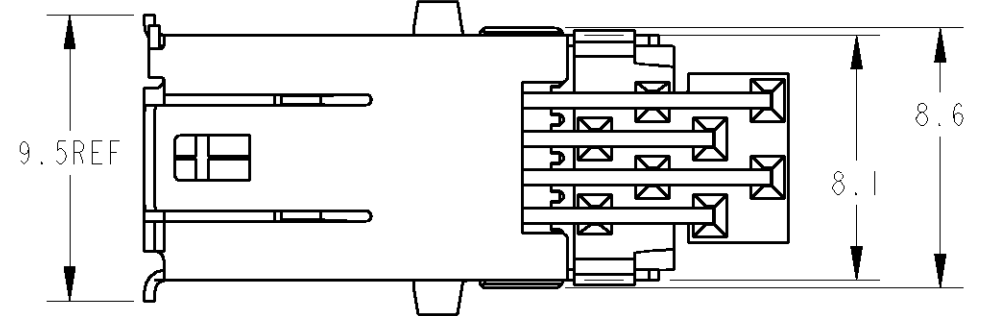
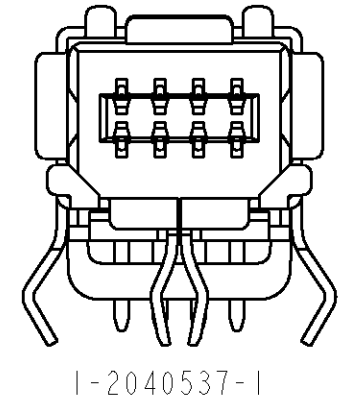
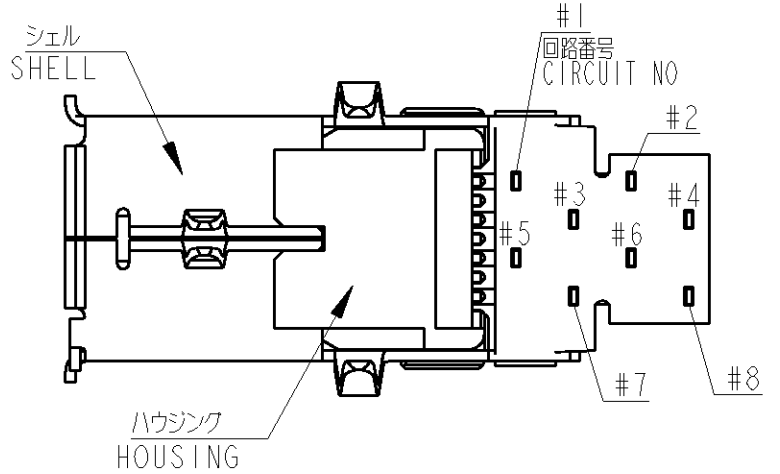


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LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
J	-		A	RELEASED	14JUL2008	M.M	I.H



推奨基板寸法 (実装面側) ±1.6
 RECOMMENDED BOARD DIMENSION (CONNECTOR SIDE) ±1.6



1. MATERIAL AND FINISH
 CONTACT
 COPPER ALLOY
 UNDER ALL SURFACE NICKEL 1.27μm MIN
 TOP CONTACT AREA : GOLD 0.5μm MIN
 SOLDERING AREA : TIN PLATE
 HOUSING
 THERMO PLASTIC (UL94V-0)
 SHELL
 COPPER ALLOY
 UNDER ALL SURFACE NICKEL
 TOP ALL SURFACE TIN

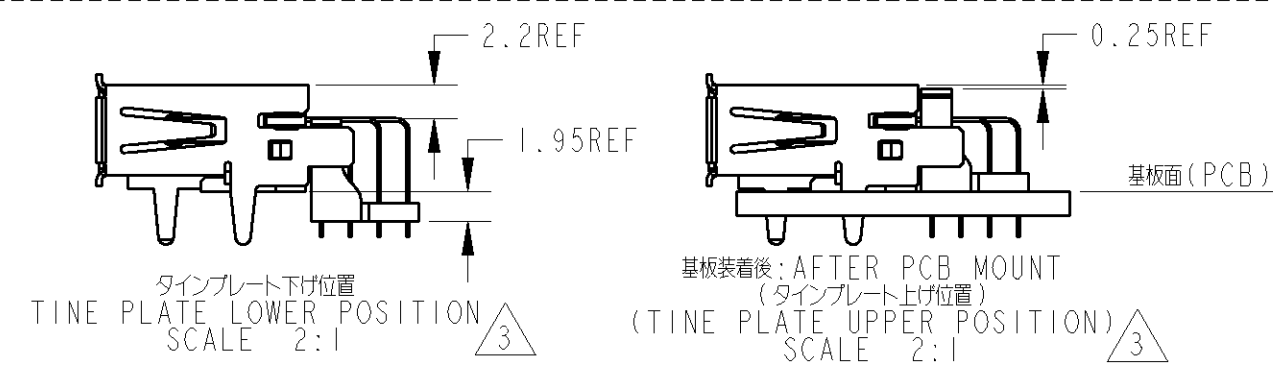
1. 材料及び仕上げ
 コンタクト
 材料: 銅合金
 全面ニッケル下地めっき 1.27μmMIN
 接点部: 金めっき 0.5μmMIN
 半田付け部: 錫めっき
 ハウジング
 材料: 熱可塑性樹脂 (難燃性UL94V-0)
 シェル
 材料: 銅合金
 全面ニッケル下地めっき
 全面錫めっき

2. DIMENSION DECIDED BY CUSTOMER.
 3. TINE PLATE CAN MOVE UP AND DOWN.

2. 顧客決定寸法
 3. タインプレートは可動式

AS SHOWN AS : 2040537-1

POS	DESCRIPTION	PART NO
8	D-SHAPE TYPE-II	1-2040537-1
8	D-SHAPE TYPE-I	2040537-1



THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.

DWN	M. MAEBASHI	14JUL2008
CHK	I. HASEGAWA	14JUL2008
APVD	I. HASEGAWA	14JUL2008

Tyco Electronics Tyco Electronics AMP K.K. Kawasaki, Japan

INDUSTRIAL MINI I/O CONN
 1.27mm PITCH
 HDR ASSY (DIP/H-TYPE) 8POS

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A3	00779	2040537	-

CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV A

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)